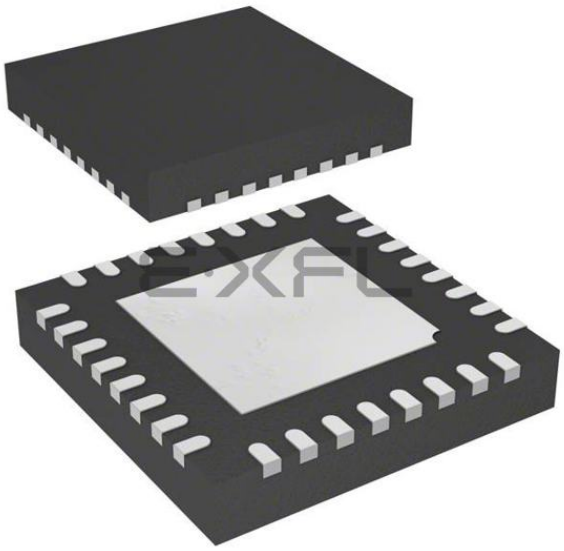

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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	ARM® Cortex®-M4
Core Size	32-Bit Single-Core
Speed	72MHz
Connectivity	I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	DMA, I²S, POR, PWM, WDT
Number of I/O	24
Program Memory Size	32KB (32K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	16K x 8
Voltage - Supply (Vcc/Vdd)	2V ~ 3.6V
Data Converters	A/D 11x12b; D/A 1x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 105°C (TA)
Mounting Type	Surface Mount
Package / Case	32-UFQFN Exposed Pad
Supplier Device Package	32-UFQFPN (5x5)
Purchase URL	https://www.e-xfl.com/product-detail/stmicroelectronics/stm32f301k6u7tr

Table 4. STM32F301x6/8 peripheral interconnect matrix

Interconnect source	Interconnect destination	Interconnect action
TIMx	TIMx	Timers synchronization or chaining
	ADC1 DAC1	Conversion triggers
	DMA	Memory to memory transfer trigger
	Compx	Comparator output blanking
COMPx	TIMx	Timer input: OCREF_CLR input, input capture
ADC1	TIM1	Timer triggered by analog watchdog
GPIO RTCCLK HSE/32 MC0	TIM16	Clock source used as input channel for HSI and LSI calibration
CSS CPU (hard fault) COMPx PVD GPIO	TIM1 TIM15, 16, 17	Timer break
GPIO	TIMx	External trigger, timer break
	ADC1 DAC1	Conversion external trigger
DAC1	COMPx	Comparator inverting input

Note: For more details about the interconnect actions, please refer to the corresponding sections in the STM32F301x6/8 and STM32F318x8 *reference manual RM0366.*

3.14 Ultra-fast comparators (COMP)

The STM32F301x6/8 devices embed up to three ultra-fast rail-to-rail comparators which offer the features below:

- Programmable internal or external reference voltage
- Selectable output polarity.

The reference voltage can be one of the following:

- External I/O
- DAC output
- Internal reference voltage or submultiple (1/4, 1/2, 3/4). Refer to *Table 27: Embedded internal reference voltage* for the value and precision of the internal reference voltage.

All comparators can wake up from STOP mode, and also generate interrupts and breaks for the timers.

3.15 Timers and watchdogs

The STM32F301x6/8 devices include advanced control timer, up to general-purpose timers, basic timer, two watchdog timers and a SysTick timer. *Table 5* compares the features of the advanced control, general purpose and basic timers.

Table 5. Timer feature comparison

Timer type	Timer	Counter resolution	Counter type	Prescaler factor	DMA request generation	Capture/ compare Channels	Complementary outputs
Advanced control	TIM1(1)	16-bit	Up, Down, Up/Down	Any integer between 1 and 65536	Yes	4	Yes
General-purpose	TIM2	32-bit	Up, Down, Up/Down	Any integer between 1 and 65536	Yes	4	No
	TIM15(1)	16-bit	Up	Any integer between 1 and 65536	Yes	2	1
	TIM16(1), TIM17(1)	16-bit	Up	Any integer between 1 and 65536	Yes	1	1
Basic	TIM6	16-bit	Up	Any integer between 1 and 65536	Yes	0	No

1. TIM1/15/16/17 can be clocked from the PLL running at 144 MHz when the system clock source is the PLL and AHB or APB2 subsystem clocks are not divided by more than 2 cumulatively.

3.18 Universal synchronous/asynchronous receiver transmitter (USART)

The STM32F301x6/8 devices have three embedded universal synchronous receiver transmitters (USART1, USART2 and USART3).

The USART interfaces are able to communicate at speeds of up to 9 Mbit/s.

All USARTs support hardware management of the CTS and RTS signals, multiprocessor communication mode, single-wire half-duplex communication mode and synchronous mode.

USART1 supports SmartCard mode, IrDA SIR ENDEC, LIN Master capability and autobaudrate detection.

All USART interfaces can be served by the DMA controller.

Refer to *Table 8* for the features available in all USARTs interfaces.

Table 8. USART features

USART modes/features(1)	USART1	USART2	USART3
Hardware flow control for modem	X	X	X
Continuous communication using DMA	X	X	X
Multiprocessor communication	X	X	X
Synchronous mode	X	X	X
SmartCard mode	X	-	-
Single-wire half-duplex communication	X	X	X
IrDA SIR ENDEC block	X	-	-
LIN mode	X	-	-
Dual clock domain and wakeup from Stop mode	X	-	-
Receiver timeout interrupt	X	-	-
Modbus communication	X	-	-
Auto baud rate detection	X	-	-
Driver Enable	X	X	X

1. X = supported.

3.19 Serial peripheral interfaces (SPI)/Inter-integrated sound interfaces (I2S)

Two SPI interfaces (SPI2 and SPI3) allow communication up to 18 Mbit/s in slave and master modes in full-duplex and simplex modes. The 3-bit prescaler gives 8 master mode frequencies and the frame size is configurable from 4 bits to 16 bits.

Two standard I2S interfaces (multiplexed with SPI2 and SPI3) are available, that can be operated in master or slave mode. These interfaces can be configured to operate with 16/32 bit resolution, as input or output channels. Audio sampling frequencies from 8 kHz up to 192 kHz are supported. When either or both of the I2S interfaces is/are configured in master

3.22 Development support

3.22.1 Serial wire JTAG debug port (SWJ-DP)

The ARM SWJ-DP Interface is embedded, and is a combined JTAG and serial wire debug port that enables either a serial wire debug or a JTAG probe to be connected to the target.

The JTAG TMS and TCK pins are shared respectively with SWDIO and SWCLK and a specific sequence on the TMS pin is used to switch between JTAG-DP and SW-DP.

Table 13. STM32F301x6/8 pin definitions (continued)

Pin Number				Pin name (function after reset)	Pin type	I/O structure	Notes	Alternate functions	Additional functions
UQFN32	WLCSP49	LQFP48	LQFP64						
20	C2	31	43	PA10	I/O	FTf	-	TIM17_BKIN, TSC_G4_IO2, I2C2_SDA, SPI2_MISO/I2S2ext_SD, TIM1_CH3, USART1_RX, COMP6_OUT, TIM2_CH4, EVENTOUT	-
21	C1	32	44	PA11	I/O	FT	-	SPI2_MOSI/I2S2_SD, TIM1_CH1N, USART1_CTS, TIM1_CH4, TIM1_BKIN2, EVENTOUT	
22	C3	33	45	PA12	I/O	FT	-	TIM16_CH1, I2SCKIN, TIM1_CH2N, USART1_RTS_DE, COMP2_OUT, TIM1_ETR, EVENTOUT	
23	B3	34	46	PA13	I/O	FT	-	SWDIO, TIM16_CH1N, TSC_G4_IO3, IR-OUT, USART3_CTS, EVENTOUT	-
-	B1	35	47	VSS_3	S	-	-	Digital ground	
-	B2	36	48	VDD_3	S	-	-	Digital power supply	
24	A1	37	49	PA14	I/O	FTf	-	SWCLK-JTCK, TSC_G4_IO4, I2C1_SDA, TIM1_BKIN, USART2_TX, EVENTOUT	-
25	A2	38	50	PA15	I/O	FTf	-	JTDI, TIM2_CH1/TIM2_ETR, TSC_SYNC, I2C1_SCL, SPI3_NSS/I2S3_WS, USART2_RX, TIM1_BKIN, EVENTOUT	-

Table 14. Alternate functions for Port A

Port & pin name	AF0	AF1	AF2	AF3	AF4	AF5	AF6	AF7	AF8	AF9	AF10	AF11	AF12	AF13	AF14	AF15
	SYS_AF	TIM2/TIM15/TIM16 /TIM17/EVENT	I2C3/TIM1/TIM2/TIM15	I2C3/TIM15/TSC	I2C1/I2C2/TIM1/ TIM16/TIM17	SPI2/I2S2/ SPI3/I2S3/Infrared	SPI2/I2S2/SPI3/ I2S3/TIM1/Infrared	USART1/USART2/USART3/ GPCOMP6	I2C3/GPCOMP2 /GPCOMP4/GPCOMP6	TIM1/TIM15	TIM2/TIM17	TIM1	TIM1	-	-	EVENT
PA0	-	TIM2 _CH1/ TIM2 _ETR	-	TSC _G1_IO1	-	-	-	USART2 _CTS	-	-	-	-	-	-	-	EVENT OUT
PA1	RTC _REFIN	TIM2 _CH2	-	TSC _G1_IO2	-	-	-	USART2 _RTS_D E	-	TIM15 _CH1N	-	-	-	-	-	EVENT OUT
PA2	-	TIM2 _CH3	-	TSC _G1_IO3	-	-	-	USART2 _TX	COMP2 _OUT	TIM15 _CH1	-	-	-	-	-	EVENT OUT
PA3	-	TIM2 _CH4	-	TSC _G1_IO4	-	-	-	USART2 _RX	-	TIM15 _CH2	-	-	-	-	-	EVENT OUT
PA4	-	-	-	TSC _G2_IO1	-	-	SPI3_NSS/ I2S3_WS	USART2 _CK	-	-	-	-	-	-	-	EVENT OUT
PA5	-	TIM2 _CH1/ TIM2 _ETR	-	TSC _G2_IO2	-	-	-	-	-	-	-	-	-	-	-	EVENT OUT
PA6	-	TIM16 _CH1	-	TSC _G2_IO3	-	-	TIM1_BKIN	-	-	-	-	-	-	-	-	EVENT OUT
PA7	-	TIM17 _CH1	-	TSC _G2_IO4	-	-	TIM1 _CH1N	-	-	-	-	-	-	-	-	EVENT OUT
PA8	MCO	-	-	I2C3 _SCL	I2C2 _SMBAL	I2S2 _MCK	TIM1_CH1	USART1 _CK	-	-	-	-	-	-	-	EVENT OUT

Table 16. Alternate functions for Port C

Port & pin name	AF0	AF1	AF2	AF3	AF4	AF5	AF6	AF7
	SYS_AF	TIM2/TIM15/ TIM16/TIM17/ EVENT	I2C3/TIM1/TIM2 /TIM15	I2C3/TIM15/ TSC	I2C1/I2C2/TIM1/ TIM16/TIM17	SPI2/I2S2/ SPI3/I2S3 Infrared	SPI2/I2S2/SPI3/ I2S3/TIM1/ Infrared	USART1/ USART2/ USART3/ GPCOMP6
PC0	-	EVENTOUT	TIM1_CH1	-	-	-	-	-
PC1	-	EVENTOUT	TIM1_CH2	-	-	-	-	-
PC2	-	EVENTOUT	TIM1_CH3	-	-	-	-	-
PC3	-	EVENTOUT	TIM1_CH4	-	-	-	TIM1_BKIN2	-
PC4	-	EVENTOUT	TIM1_ETR	-	-	-	-	USART1_TX
PC5	-	EVENTOUT	TIM15_BKIN	TSC_G3_IO1	-	-	-	USART1_RX
PC6	-	EVENTOUT	-	-	-	-	I2S2_MCK	COMP6_OUT
PC7	-	EVENTOUT	-	-	-	-	I2S3_MCK	-
PC8	-	EVENTOUT	-	-	-	-	-	-
PC9	-	EVENTOUT	-	I2C3_SDA	-	I2SCKIN	-	-
PC10	-	EVENTOUT	-	-	-	-	SPI3_SCK/ I2S3_CK	USART3_TX
PC11	-	EVENTOUT	-	-	-	-	SPI3_MISO/ I2S3ext_SD	USART3_RX
PC12	-	EVENTOUT	-	-	-	-	SPI3_MOSI/ I2S3_SD	USART3_CK
PC13	-	-	-	-	TIM1_CH1N	-	-	-
PC14	-	-	-	-	-	-	-	-
PC15	-	-	-	-	-	-	-	-

6.3.4 Embedded reference voltage

The parameters given in *Table 27* are derived from tests performed under ambient temperature and V_{DD} supply voltage conditions summarized in *Table 23*.

Table 27. Embedded internal reference voltage

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{REFINT}	Internal reference voltage	–40 °C < T_A < +105 °C	1.20	1.23	1.25	V
$T_{S\_vrefint}$	ADC sampling time when reading the internal reference voltage	-	2.2	-	-	µs
V_{RERINT}	Internal reference voltage spread over the temperature range	V_{DD} = 3 V ±10 mV	-	-	10(1)	mV
T_{Coeff}	Temperature coefficient	-	-	-	100 (1)	ppm/°C

1. Guaranteed by design.

Table 28. Internal reference voltage calibration values

Calibration value name	Description	Memory address
V_{REFINT_CAL}	Raw data acquired at temperature of 30 °C V_{DDA}= 3.3 V	0x1FFF F7BA - 0x1FFF F7BB

6.3.5 Supply current characteristics

The current consumption is a function of several parameters and factors such as the operating voltage, ambient temperature, I/O pin loading, device software configuration, operating frequencies, I/O pin switching rate, program location in memory and executed binary code.
The current consumption is measured as described in *Figure 12: Current consumption measurement scheme*.
All Run-mode current consumption measurements given in this section are performed with a reduced code that gives a consumption equivalent to CoreMark code.

Note: The total current consumption is the sum of I_{DD} and I_{DDA}.

Low-speed external user clock generated from an external source

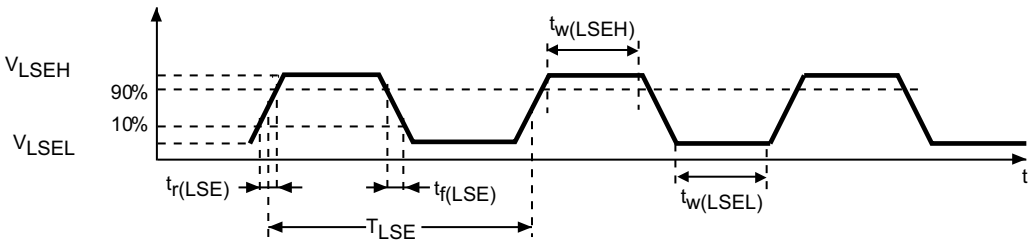
In bypass mode the LSE oscillator is switched off and the input pin is a standard GPIO. The external clock signal has to respect the I/O characteristics in *Section 6.3.14*. However, the recommended clock input waveform is shown in *Figure 15*

Table 41. Low-speed external user clock characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
f_{LSE_ext}	User External clock source frequency(1)	-	-	32.768	1000	kHz
V_{LSEH}	OSC32_IN input pin high level voltage		$0.7V_{DD}$	-	V_{DD}	V
V_{LSEL}	OSC32_IN input pin low level voltage		V_{SS}	-	$0.3V_{DD}$	
$t_{w(LSEH)}$ $t_{w(LSEL)}$	OSC32_IN high or low time(1)		450	-	-	ns
$t_{r(LSE)}$ $t_{f(LSE)}$	OSC32_IN rise or fall time(1)		-	-	50	

1. Guaranteed by design.

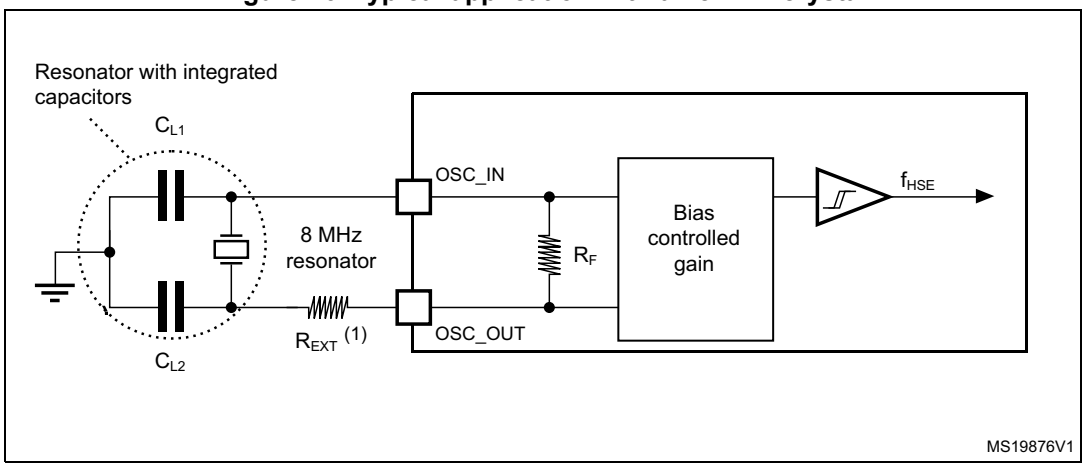
Figure 15. Low-speed external clock source AC timing diagram



For C_{L1} and C_{L2}, it is recommended to use high-quality external ceramic capacitors in the 5 pF to 25 pF range (Typ.), designed for high-frequency applications, and selected to match the requirements of the crystal or resonator (see *Figure 16*). C_{L1} and C_{L2} are usually the same size. The crystal manufacturer typically specifies a load capacitance which is the series combination of C_{L1} and C_{L2}. PCB and MCU pin capacitance must be included (10 pF can be used as a rough estimate of the combined pin and board capacitance) when sizing C_{L1} and C_{L2}.

Note: For information on selecting the crystal, refer to the application note AN2867 "Oscillator design guide for ST microcontrollers" available from the ST website www.st.com.

Figure 16. Typical application with an 8 MHz crystal



1. R_{EXT} value depends on the crystal characteristics.

Input/output AC characteristics

The definition and values of input/output AC characteristics are given in *Figure 23* and *Table 56*, respectively.

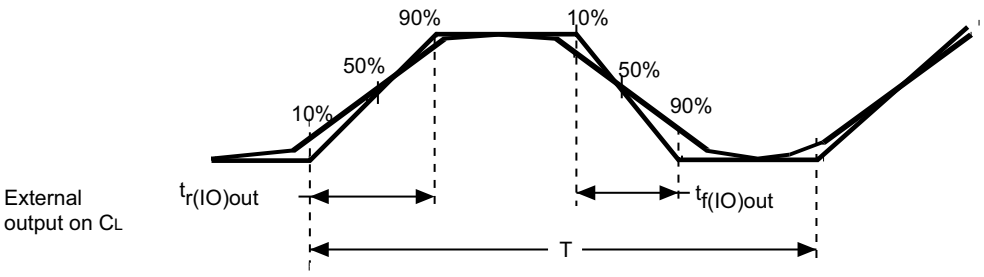
Unless otherwise specified, the parameters given are derived from tests performed under ambient temperature and V_{DD} supply voltage conditions summarized in *Table 23*.

Table 56. I/O AC characteristics(1)

OSPEEDRy [1:0] value(1)	Symbol	Parameter	Conditions	Min	Max	Unit
x0	$f_{max(IO)out}$	Maximum frequency(2)	C_L = 50 pF, V_{DD} = 2 V to 3.6 V	-	2(3)	MHz
	$t_{f(IO)out}$	Output high to low level fall time	C_L = 50 pF, V_{DD} = 2 V to 3.6 V	-	125(3)	ns
	$t_{r(IO)out}$	Output low to high level rise time		-	125(3)	
01	$f_{max(IO)out}$	Maximum frequency(2)	C_L = 50 pF, V_{DD} = 2 V to 3.6 V	-	10(3)	MHz
	$t_{f(IO)out}$	Output high to low level fall time	C_L = 50 pF, V_{DD} = 2 V to 3.6 V	-	25(3)	ns
	$t_{r(IO)out}$	Output low to high level rise time		-	25(3)	
11	$f_{max(IO)out}$	Maximum frequency(2)	C_L = 30 pF, V_{DD} = 2.7 V to 3.6 V	-	50(3)	MHz
			C_L = 50 pF, V_{DD} = 2.7 V to 3.6 V	-	30(3)	MHz
			C_L = 50 pF, V_{DD} = 2 V to 2.7 V	-	20(3)	MHz
	$t_{f(IO)out}$	Output high to low level fall time	C_L = 30 pF, V_{DD} = 2.7 V to 3.6 V	-	5(3)	ns
			C_L = 50 pF, V_{DD} = 2.7 V to 3.6 V	-	8(3)	
			C_L = 50 pF, V_{DD} = 2 V to 2.7 V	-	12(3)	
	$t_{r(IO)out}$	Output low to high level rise time	C_L = 30 pF, V_{DD} = 2.7 V to 3.6 V	-	5(3)	
			C_L = 50 pF, V_{DD} = 2.7 V to 3.6 V	-	8(3)	
			C_L = 50 pF, V_{DD} = 2 V to 2.7 V	-	12(3)	
FM+ configuration(4)	$f_{max(IO)out}$	Maximum frequency(2)	C_L = 50 pF, V_{DD} = 2 V to 3.6 V	-	2(4)	MHz
	$t_{f(IO)out}$	Output high to low level fall time		-	12(4)	ns
	$t_{r(IO)out}$	Output low to high level rise time		-	34(4)	
-	t_{EXTIpw}	Pulse width of external signals detected by the EXTI controller	-	10	-‘	ns

1. The I/O speed is configured using the OSPEEDRx[1:0] bits. Refer to the RM0366 reference manual for a description of GPIO Port configuration register.
2. The maximum frequency is defined in *Figure 23*.
3. Guaranteed by design.
4. The I/O speed configuration is bypassed in FM+ I/O mode. Refer to the STM32F301x6 STM32F301x8 reference manual RM0366 for a description of FM+ I/O mode configuration.

Figure 23. I/O AC characteristics definition



Maximum frequency is achieved if $(t_r + t_f) \leq 2/3)T$ and if the duty cycle is (45-55%)
when loaded by C_L (see note 1).

MS34942V1

1. See *Table 56: I/O AC characteristics*.

6.3.15 NRST pin characteristics

The NRST pin input driver uses CMOS technology. It is connected to a permanent pull-up resistor, R_{PU} (see *Table 54*).

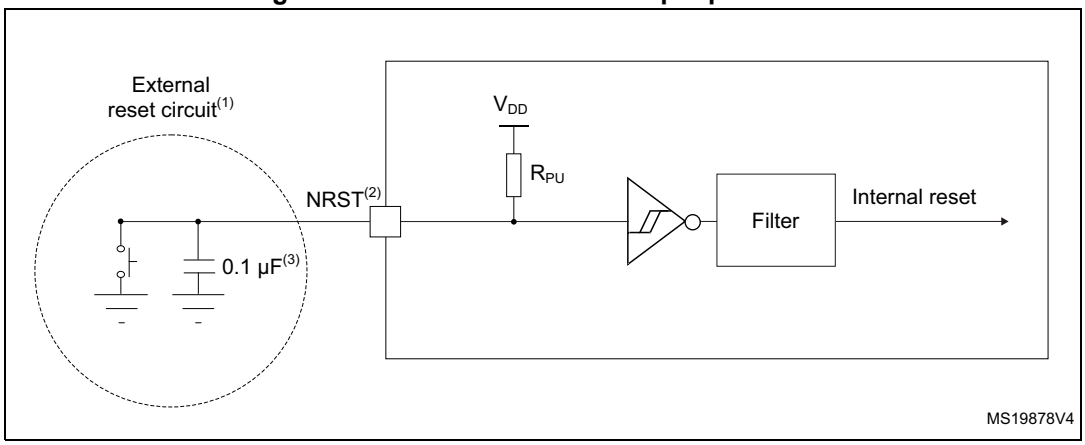
Unless otherwise specified, the parameters given in *Table 57* are derived from tests performed under ambient temperature and V_{DD} supply voltage conditions summarized in *Table 23*.

Table 57. NRST pin characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{IL(NRST)}$(1)	NRST Input low level voltage	-	-	-	$0.3V_{DD}$+ 0.07(1)	V
$V_{IH(NRST)}$(1)	NRST Input high level voltage	-	$0.445V_{DD}$+ 0.398(1)	-	-	
$V_{hys(NRST)}$	NRST Schmitt trigger voltage hysteresis	-	-	200	-	mV
R_{PU}	Weak pull-up equivalent resistor(2)	$V_{IN} = V_{SS}$	25	40	55	kΩ
$V_{F(NRST)}$(1)	NRST Input filtered pulse	-	-	-	100(1)	ns
$V_{NF(NRST)}$(1)	NRST Input not filtered pulse	-	500(1)	-	-	ns

1. Guaranteed by design.
2. The pull-up is designed with a true resistance in series with a switchable PMOS. This PMOS contribution to the series resistance must be minimum (~10% order).

Figure 24. Recommended NRST pin protection



1. The reset network protects the device against parasitic resets.
2. The user must ensure that the level on the NRST pin can go below the $V_{IL(NRST)}$ max level specified in *Table 57*. Otherwise the reset will not be taken into account by the device.
3. The user must place the external capacitor on NRST as close as possible to the chip.

6.3.16 Timer characteristics

The parameters given in *Table 58* are guaranteed by design.

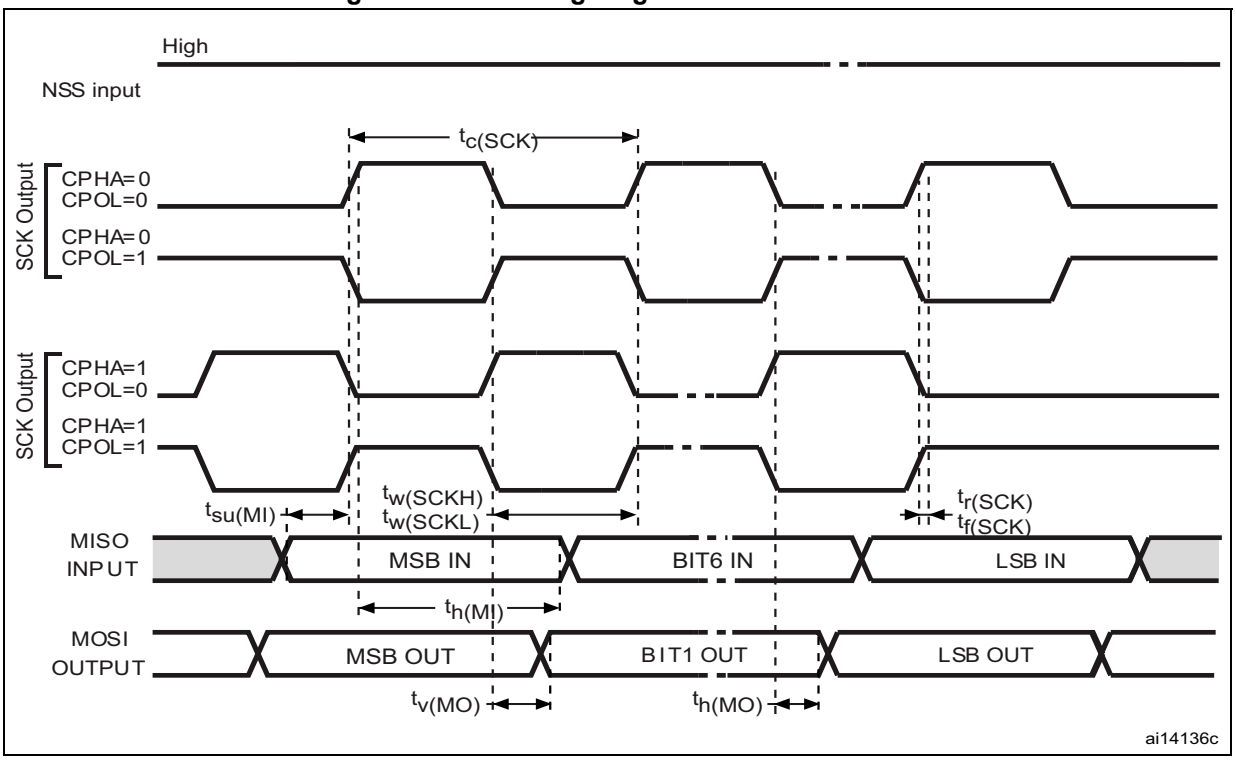
Refer to *Section 6.3.14: I/O port characteristics* for details on the input/output alternate function characteristics (output compare, input capture, external clock, PWM output).

Table 58. TIMx(1)(2) characteristics

Symbol	Parameter	Conditions	Min	Max	Unit
$t_{res(TIM)}$	Timer resolution time	-	1	-	$t_{TIMxCLK}$
		$f_{TIMxCLK}$ = 72 MHz	13.9	-	ns
		$f_{TIMxCLK}$ = 144 MHz, x = 1, 15,16, 17	6.95	-	ns
f_{EXT}	Timer external clock frequency on CH1 to CH4	-	0	$f_{TIMxCLK}/2$	MHz
		$f_{TIMxCLK}$ = 72 MHz	0	36	MHz
Res_{TIM}	Timer resolution	TIMx (except TIM2)	-	16	bit
		TIM2	-	32	
$t_{COUNTER}$	16-bit counter clock period	-	1	65536	$t_{TIMxCLK}$
		$f_{TIMxCLK}$ = 72 MHz	0.0139	910	µs
		$f_{TIMxCLK}$ = 144 MHz, x= 1/15/16/17	0.0069	455	µs
t_{MAX_COUNT}	Maximum possible count with 32-bit counter	-	-	65536 × 65536	$t_{TIMxCLK}$
		$f_{TIMxCLK}$ = 72 MHz	-	59.65	s
		$f_{TIMxCLK}$ = 144 MHz, x= 1/15/16/17	-	29.825	s

1. TIMx is used as a general term to refer to the TIM1, TIM2, TIM15, TIM16 and TIM17 timers.
2. Guaranteed by design.

Figure 27. SPI timing diagram - master mode(1)



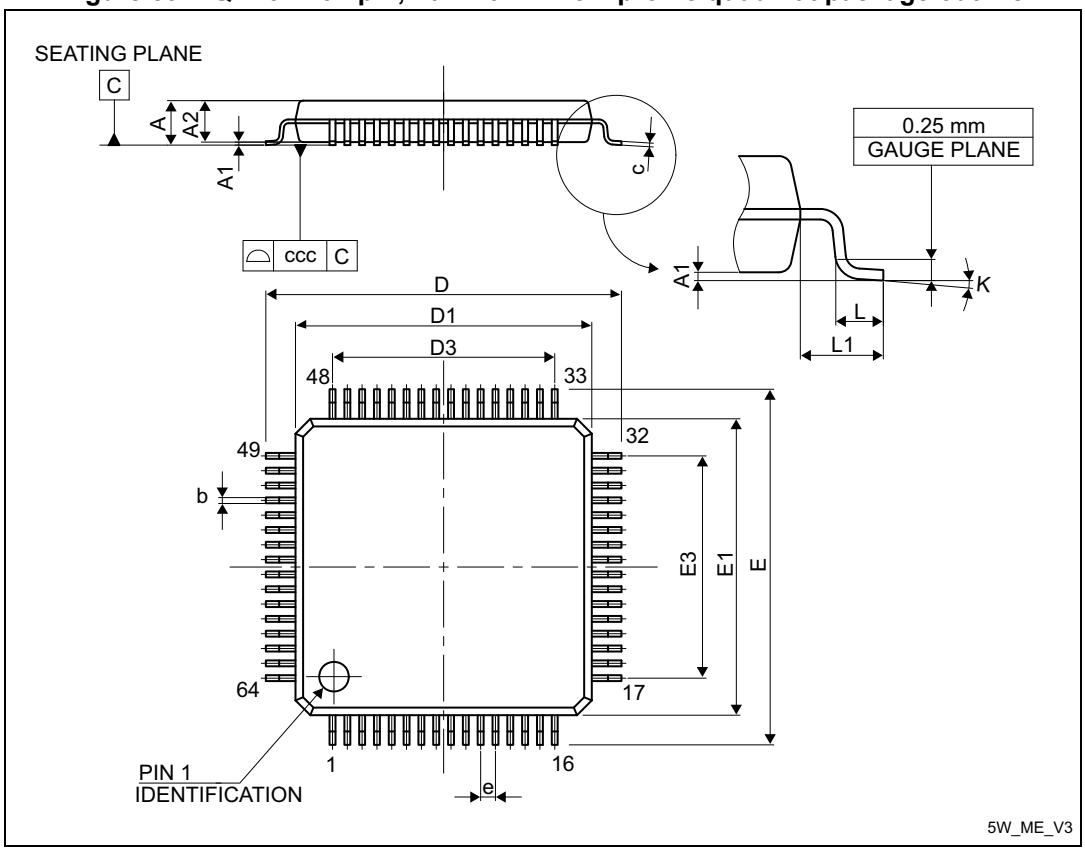
1. Measurement points are done at $0.5V_{DD}$ and with external C_L = 30 pF.

Table 63. I2S characteristics(1)

Symbol	Parameter	Conditions	Min	Max	Unit
f_{MCK}	I2S Main clock output	-	256 x 8K	256xFs (2)	MHz
f_{CK}	I2S clock frequency	Master data: 32 bits	-	64xFs	MHz
		Slave data: 32 bits	-	64xFs	
D_{CK}	I2S clock frequency duty cycle	Slave receiver	30	70	%

7.2 LQFP64 package information

Figure 39. LQFP64 - 64-pin, 10 x 10 mm low-profile quad flat package outline



1. Drawing is not to scale.

Table 77. LQFP64 - 64-pin, 10 x 10 mm low-profile quad flat package mechanical data

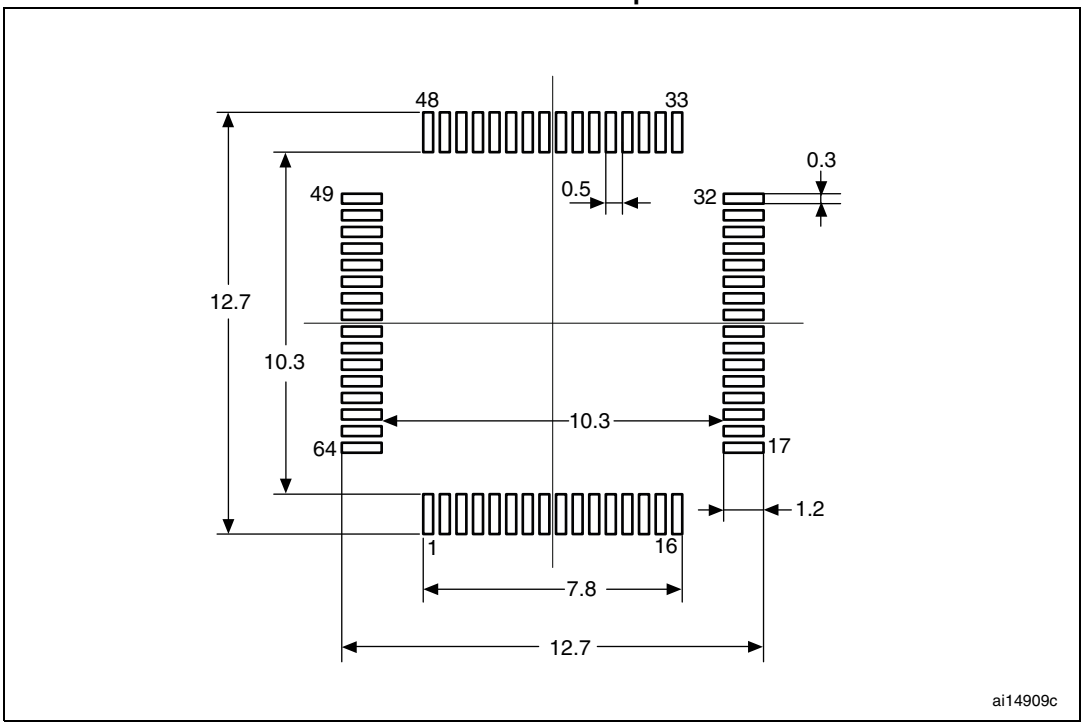
Symbol	millimeters			inches[1]		
	Min	Typ	Max	Min	Typ	Max
A	-	-	1.600	-	-	0.0630
A1	0.050	-	0.150	0.0020	-	0.0059
A2	1.350	1.400	1.450	0.0531	0.0551	0.0571
b	0.170	0.220	0.270	0.0067	0.0087	0.0106
c	0.090	-	0.200	0.0035	-	0.0079
D	-	12.000	-	-	0.4724	-
D1	-	10.000	-	-	0.3937	-
D3	-	7.500	-	-	0.2953	-
E	-	12.000	-	-	0.4724	-
E1	-	10.000	-	-	0.3937	-

Table 77. LQFP64 - 64-pin, 10 x 10 mm low-profile quad flat package mechanical data (continued)

Symbol	millimeters			inches[1]		
	Min	Typ	Max	Min	Typ	Max
E3	-	7.500	-	-	0.2953	-
e	-	0.500	-	-	0.0197	-
K	0°	3.5°	7°	0°	3.5°	7°
L	0.450	0.600	0.750	0.0177	0.0236	0.0295
L1	-	1.000	-	-	0.0394	-
ccc	-	-	0.080	-	-	0.0031

1. Values in inches are converted from mm and rounded to 4 decimal digits.

Figure 40. LQFP64 - 64-pin, 10 x 10 mm low-profile quad flat package recommended footprint



1. Dimensions are expressed in millimeters.

Table 78. LQFP48 - 48-pin, 7 x 7 mm low-profile quad flat package mechanical data

Symbol	millimeters			inches[1]		
	Min	Typ	Max	Min	Typ	Max
A	-	-	1.600	-	-	0.0630
A1	0.050	-	0.150	0.0020	-	0.0059
A2	1.350	1.400	1.450	0.0531	0.0551	0.0571
b	0.170	0.220	0.270	0.0067	0.0087	0.0106
c	0.090	-	0.200	0.0035	-	0.0079
D	8.800	9.000	9.200	0.3465	0.3543	0.3622
D1	6.800	7.000	7.200	0.2677	0.2756	0.2835
D3	-	5.500	-	-	0.2165	-
E	8.800	9.000	9.200	0.3465	0.3543	0.3622
E1	6.800	7.000	7.200	0.2677	0.2756	0.2835
E3	-	5.500	-	-	0.2165	-
e	-	0.500	-	-	0.0197	-
L	0.450	0.600	0.750	0.0177	0.0236	0.0295
L1	-	1.000	-	-	0.0394	-
k	0°	3.5°	7°	0°	3.5°	7°
ccc	-	-	0.080	-	-	0.0031

1. Values in inches are converted from mm and rounded to 4 decimal digits.

7.5.2 Selecting the product temperature range

When ordering the microcontroller, the temperature range is specified in the ordering information scheme shown in *Section 8: Ordering information*.

Each temperature range suffix corresponds to a specific guaranteed ambient temperature at maximum dissipation and, to a specific maximum junction temperature.

As applications do not commonly use the STM32F301x6 STM32F301x8 at maximum dissipation, it is useful to calculate the exact power consumption and junction temperature to determine which temperature range will be best suited to the application.

The following examples show how to calculate the temperature range needed for a given application.

Example 1: High-performance application

Assuming the following application conditions:

Maximum ambient temperature T_{Amax} = 82 °C (measured according to JESD51-2), I_{DDmax} = 50 mA, V_{DD} = 3.5 V, maximum 3 I/Os used at the same time in output at low level with I_{OL} = 8 mA, V_{OL}= 0.4 V and maximum 2 I/Os used at the same time in output at low level with I_{OL} = 20 mA, V_{OL}= 1.3 V

P_{INTmax} = 50 mA × 3.5 V= 175 mW

P_{IOmax} = 3 × 8 mA × 0.4 V + 2 × 20 mA × 1.3 V = 61.6 mW

This gives: P_{INTmax} = 175 mW and P_{IOmax} = 61.6 mW:

P_{Dmax} = 175 + 61.6 = 236.6 mW

Thus: P_{Dmax} = 236.6 mW

Using the values obtained in *Table 80* T_{Jmax} is calculated as follows:

– For LQFP64, 45°C/W

T_{Jmax} = 82 °C + (45°C/W × 236.6 mW) = 82°C + 10.65 °C = 92.65°C

This is within the range of the suffix 6 version parts (–40 < T_J < 105 °C).

In this case, parts must be ordered at least with the temperature range suffix 6 (see *Section 8: Ordering information*).